MP6215
.3V/5V, Single-Channel 1.5A Current-Limited Power Distribution Switch

The Future of Analog IC Technology

DESCRIPTION

The MP6215 Power Distribution Switch features internal curr ent limiting to prevent   damage to host device s due to fau lty load con ditions. The MP6215 op erates from a 3.3V or   5V nominal input voltage and includes a 90   mΩ Power MOSFET to handle up t o 1.5A cont inuous load with a 2.3A typical curr ent limit. T he MP6215 has built-in protection fo r both over current and increased   thermal stress. For   over-current protection (OCP), the device will limit th   e current by going into a constant current mode.

When continuous outp ut overload condition exceeds power dissipat ion of the package, the thermal protection will   shut the pa rt off. The device will recover once the device temperature reduces to approx 120°C.

The MP6215 is available in an MSOP8 package with exposed pad.

FEATURES

- 1.5A Continuous Current
- Accurate Current Limit
- 2.7V to 5.5V Supply Range
- 140uA Quiescent Current
- Thermal-Sh utdown Protection
- Under-Voltage   Lockout
- 8ms FLAG Deglitch Time
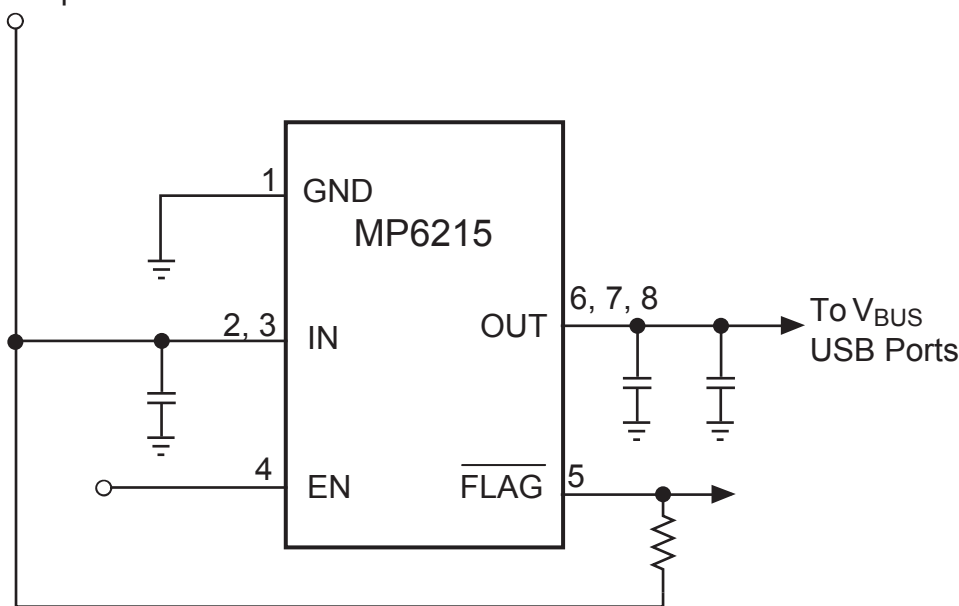- No FLAG Glitch During Power Up
- Reverse Current Blocking

APPLICATIONS

- Notebook   PC
- Set-top-box
- Telecom and Network Systems
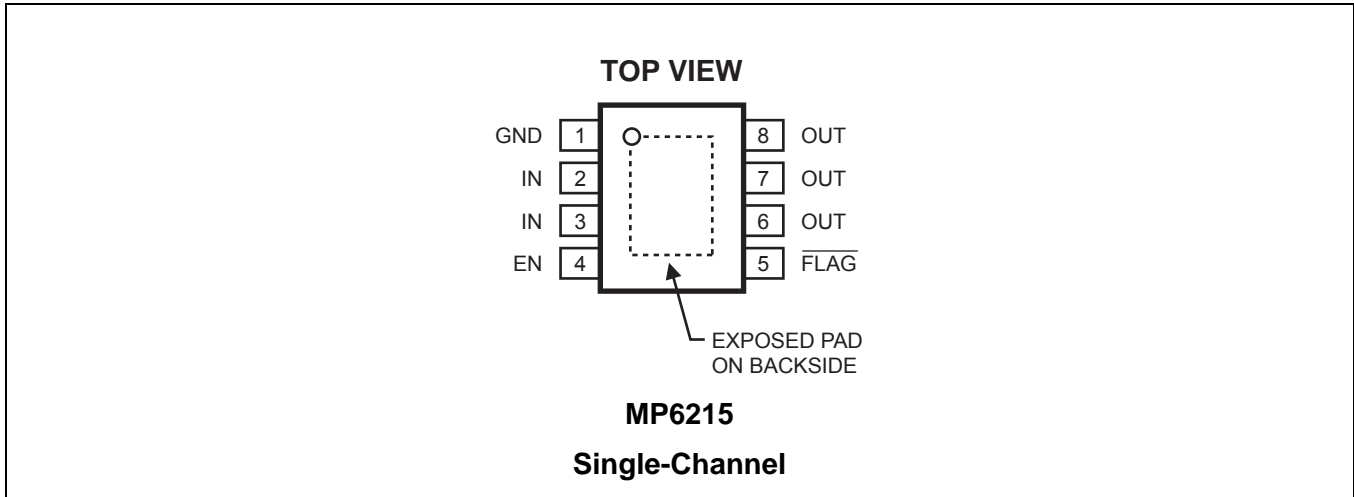- PC Card Hot Swap
- USB Power Distribution

"MPS" and "The Future of Analog IC Technology" are Trademarks of Monolithic Power Systems, Inc.

TYPICAL APPLICATION

3.3V / 5V Input

SINGLE-CHANNEL

PACKAGE REFERENCE

TOP VIEW

```
GND  1        8  OUT
IN   2        7  OUT
IN   3        6  OUT
EN   4        5  FLAG
```

EXPOSED PAD
ON BACKSIDE

MP6215

Single-Channel

Part Number	Enable	Switch	Maximum Continuous Load Current	Typical Short-Circuit Current @ T_A=25C	Package	Temperature
MP6215DH	Active High	Single	1.5A	2.3A	MSOP8 (EP)	–40°C to +85°C

* For Tape & Reel, add suffix –Z (eg. MP6215DH–Z)
For RoHS Compliant Packaging, add suffix –LF
(eg. MP6215DH–LF–Z)

ABSOLUTE MAXIMUM RATINGS [1]

IN ....-0.3V to +6.5V
ON, FLAG, OUT to GND..............-0.3V to +6.5V
Junction Temperature..............................150°C
Lead Temperature ....260°C
Storage Temperature...............–65°C to +150°C
Operating Temperature..............–40°C to +85°C

Thermal Resistance [2] θ_{JA} θ_{JC}
MSOP8E................................. 55 ...... 12... °C/W

Notes:
1) Exceeding these ratings may damage the device.
2) Measured on JESD51-7, 4-layer PCB..

ELECTRICAL CHARACTERISTICS [3]

V_{IN}=5V, T_A=+25°C, unless otherwise noted.

Parameter	Condition	Min	Typ	Max	Units
IN Voltage Range	2.7			5.5	V
Supply Current	EN=High, I_{OUT}=0		140	160	μA
Shutdown Current	Device Disable, V_{OUT}=float, V_{IN}=5.5V		1		μA
Off Switch Leakage	Device Disable, V_{IN}=5.5V		1		μA
Current Limit	1.6		2.3	3.0	A
Under-voltage Lockout	Rising Edge	1.95		2.65	V
Under-voltage Hysteresis			250		mV
FET On Resistance	I_{OUT}=100mA		85		mΩ
EN Input Logic High Voltage	2				V
EN Input Logic Low Voltage				0.4	V
FLAG Output Logic Low Voltage	I_{SINK}=5mA			0.4	V
FLAG Output High Leakage Current	V_{IN}=V_{FLAG}=5.5V			1	μA
Thermal Shutdown			140		°C
Thermal Shutdown Hysteresis			20		°C
V_{OUT} Rising Time, Tr	V_{IN}=5.5V, CL=1uF, RL=5Ω	0.9			ms
	V_{IN}=2.7V, CL=1uF, RL=5Ω	1.7			ms
V_{OUT} Falling Time, Tf	V_{IN}=5.5V, CL=1uF, RL=5Ω			0.5	ms
	V_{IN}=2.7V, CL=1uF, RL=5Ω			0.5	ms
Turn On Time, Ton	C_L=100μF, RL=5Ω			3	ms
Turn Off Time, Toff	C_L=100μF, RL=5Ω			10	ms
FLAG Deglitch Time		4	8	15	ms
EN Input Leakage	-1				μA
Reverse Leakage Current	OUT=5.5V, IN=GND		0.2		μA

NOTE:
3) Production test at +25°C. Specifications over the temperature range are guaranteed by design and characterization.

PIN FUNCTIONS

MSOP8E	Name	Description
1	GND	Ground.
2, 3	IN	Input Voltage. Accepts 2.7V to 5.5V input.
4	EN	Active High
5	$\overline{\text{FLAG}}$	IN-to-OUT Over-current, active-low output flag. Open-Drain.
6, 7, 8	OUT	IN-to-OUT Power-Distribution Output (for all 3 output pins)

TYPICAL PERFORMANCE CHARACTERISTICS
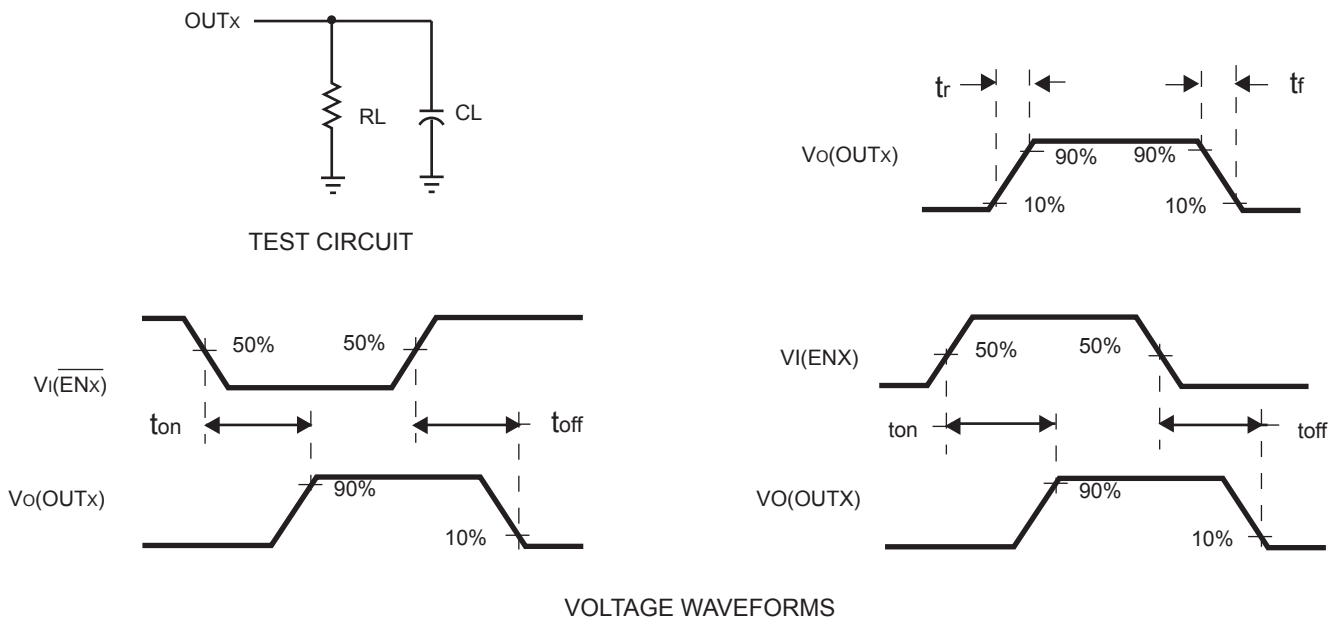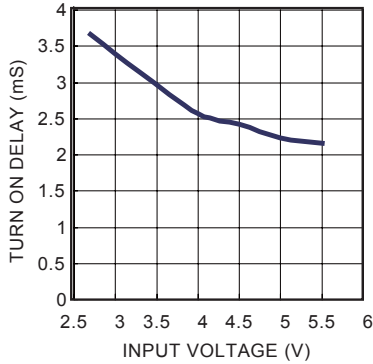
T_A = +25ºC, unless otherwise noted.

VOLTAGE WAVEFORMS
Figure 1—Test Circuit and Voltage Waveforms

TYPICAL PERFORMANCE CHARACTERISTICS

T_A = +25⁰C, unless otherwise noted.

Turn on Delay vs. Input Votage
V_{EN}=5V, I_O=1.5A, C_L=2.2uF

Turn off Delay vs. Input Votage
V_{EN}=5V, I_O=1.5A, C_L=2.2uF
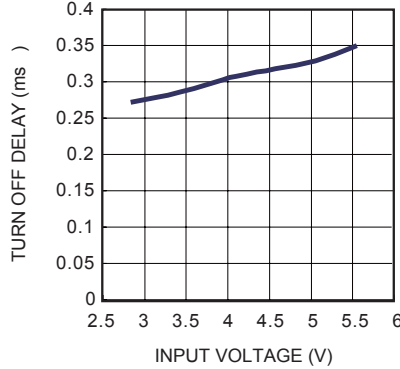
Supply Current, Output Enabled vs. Input Voltage
V_{EN}=5V, C_L=2.2uF
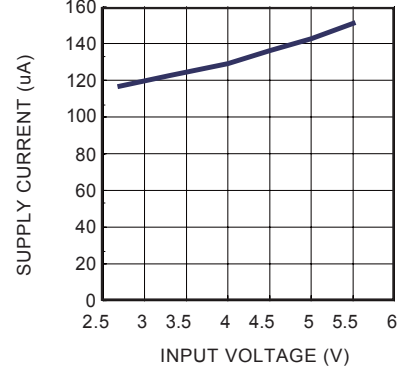
Supply Current, Output Disabled vs. Input Voltage
V_{EN}=0V, C_L=2.2uF
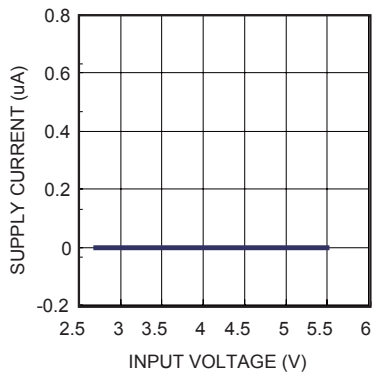
Static Drain-Source On-State Resistance vs. Input Voltage
V_{EN}=5V, I_{OUT}=1.5A, C_L=2.2uF
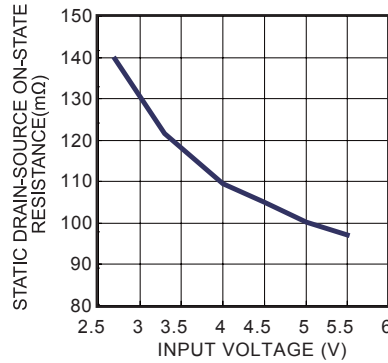
Input to Output Voltage vs. Load Current
V_{EN}=5V, C_L=2.2uF
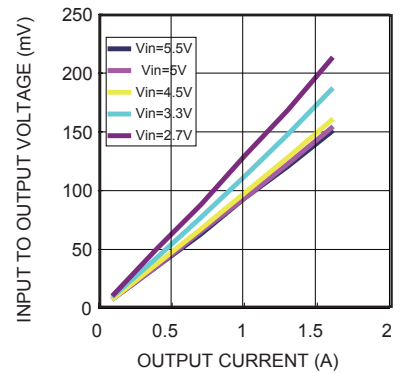
Current Limit vs. Input Voltage
V_{EN}=5V, C_L=2.2uF
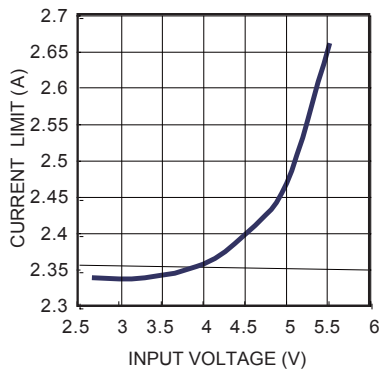
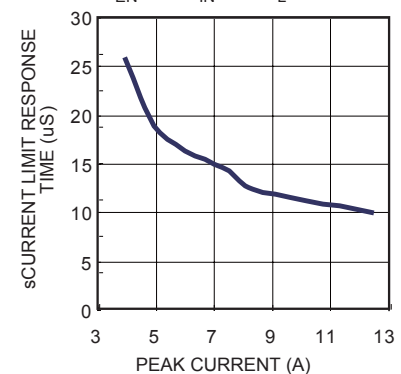**Threshold Trip Current vs. Input Voltage**
V_{EN}=5V, C_L=2.2uF
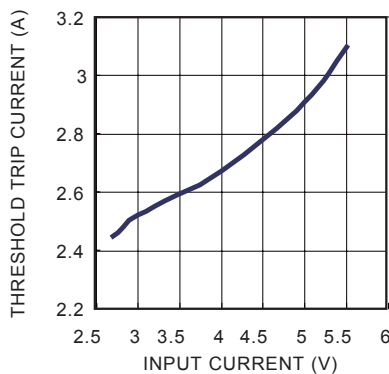
Current Limit Response Time vs. Peak Voltage
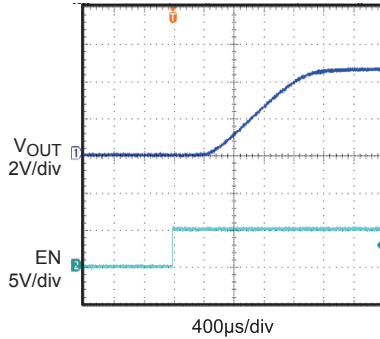V_{EN}=5V, V_{IN}=5V, C_L=2.2uF

TYPICAL PERFORMANCE CHARACTERISTICS

T_A = +25⁰C, unless otherwise noted. *(continued)*

Turn On Delay and Rise Time with 0.22uF Load
V_{IN}=5V, V_{EN}=5V, RL=3.3Ω, C_L=0.22uF

400µs/div

Turn Off Delay and Fall Time with 0.22uF Load
V_{IN}=5V, V_{EN}=5V, RL=3.3Ω, C_L=0.22uF
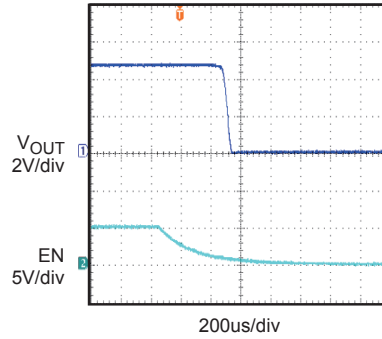
200us/div

Turn On Delay and Rise Time with 2.2uF Load
V_{IN}=5V, V_{EN}=5V, RL=3.3Ω, C_L=2.2uF

400µs/div
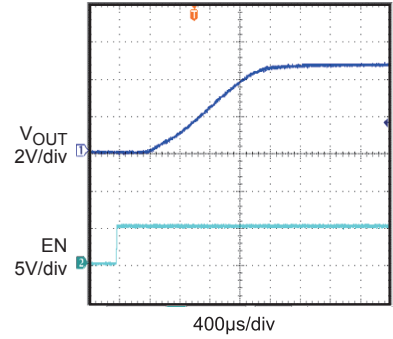
Turn Off Delay and Fall Time with 2.2uF Load
V_{IN}=5V, V_{EN}=5V, RL=3.3Ω, C_L=2.2uF

200µs/div
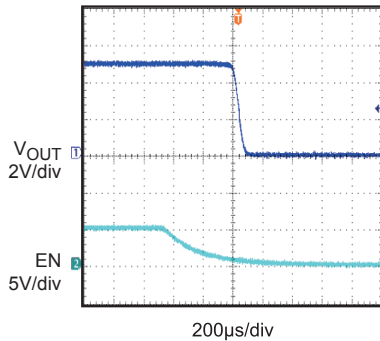
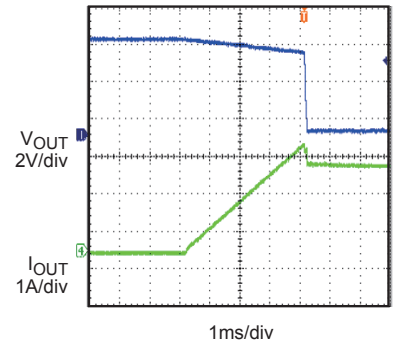**Short Circuit Current Device Enabled into Short**
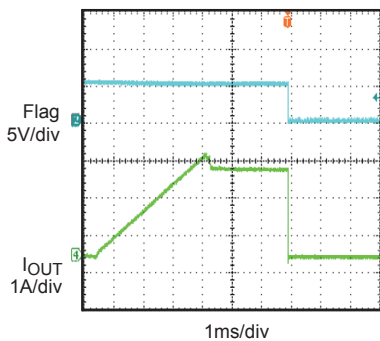V_{IN}=5V, V_{EN}=5V, C_L=2.2uF

400µs/div
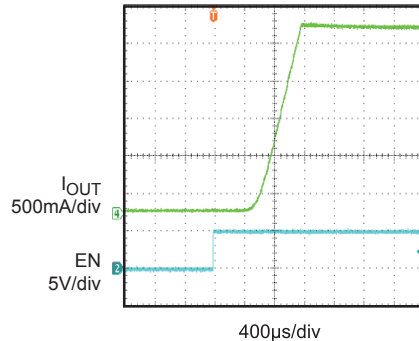
Threshold Trip Current with Ramped Load on Enabled Device
V_{IN}=5V, V_{EN}=5V, C_L=2.2uF

1ms/div

Ramped Load on Enabled Device
V_{IN}=5V, V_{EN}=5V, C_L=2.2uF

1ms/div

Inrush Current with Different Load Capacitance
V_{IN}=5V, V_{EN}=5V, R_L=3.3Ω, Start up by EN

220uF
470uF
100uF

1ms/div
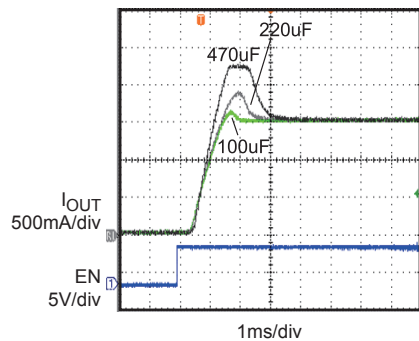
1Ω Load Connected to Enabled Device
V_{IN}=5V, V_{EN}=5V, C_L=2.2uF

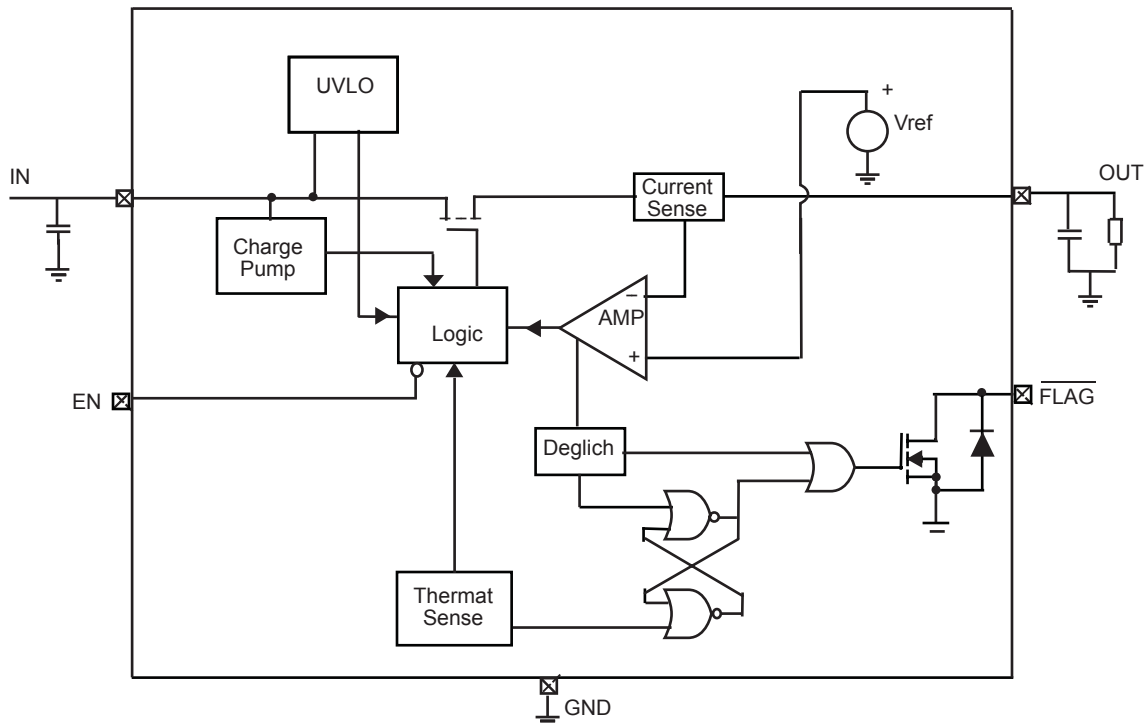2ms/div
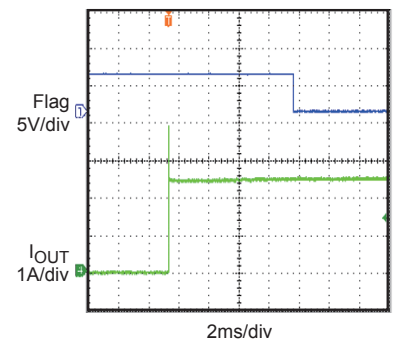
FUNCTION BLOCK DIAGRAM

Figure2—Functional Block Diagram

DETAILED DESCRIPTION

Over Current
When the load exceeds trip current (minimum threshold current triggering constant-current mode) or a short is present, MP6215 switches into to a constant-current mode (current limit value). MP6215 will be shutdown only if the overcurrent condition stays long enough to trigger thermal protection.

Trigger overcurrent protection for different overload conditions occurring in applications:
1) The output has been shorted or overloaded before the device is enabled or input applied. MP6215 detects the short or overload and immediately switches into a constant-current mode.
2) A short or an overload occurs after the device is enabled. After the current-limit circuit has been tripped (reached the trip current threshold), the device switches into constant-current mode. However, high current may flow for a short period of time before the current-limit circuit can react.

3) Output current has been gradually increased beyond the recommended operating current. The load current rises until the trip current threshold is reached or until the thermal limit of the device is exceeded. The MP6215 is capable of delivering current up to the trip current threshold without damaging the device. Once the trip threshold has been reached, the device switches into its constant-current mode.

Flag Response
The FLAG pin is an open drain configuration. This FAULT will report a fail mode after an 8ms deglitch timeout. This is used to ensure that no false fault signals are reported. This internal deglitch circuit eliminates the need for extend components. The FLAG pin is not deglitched during an over temp. or a voltage lockout.

Thermal Protection

The purpose of thermal protect ion is to prevent damage in the IC by allowing exceptive current to flow and heating the junction. The die temperature is internally monitored until the thermal limit is reached. Once this temperature is reached, th e switch will turn off a nd allow the chip to cool. The switch has a built-in hysteresis.

Under-voltage Lockout (UVLO)

This circuit is used to monitor the input voltage t o ensure that the MP6215 is operating correctly.

This UVLO circu it a lso ensures that is n o operation u ntil the inp ut voltage reaches th e minimum spec.

Enable

The logic pin disables the switch to redu ce overall supply current .Once the EN pin reaches
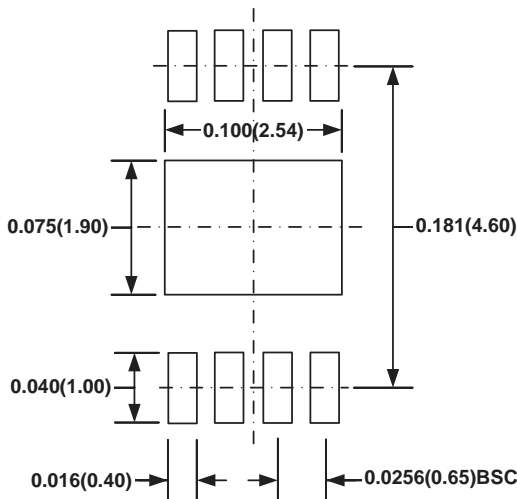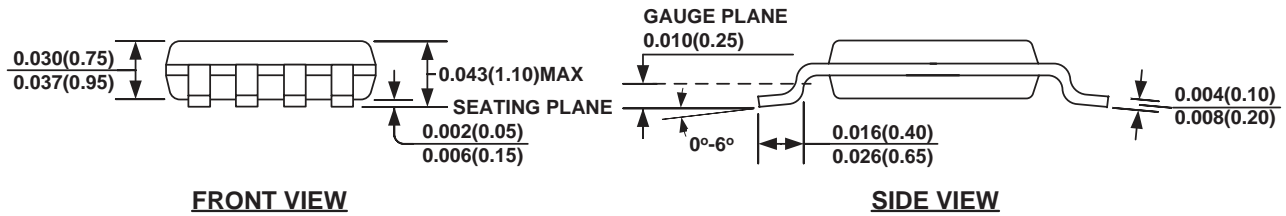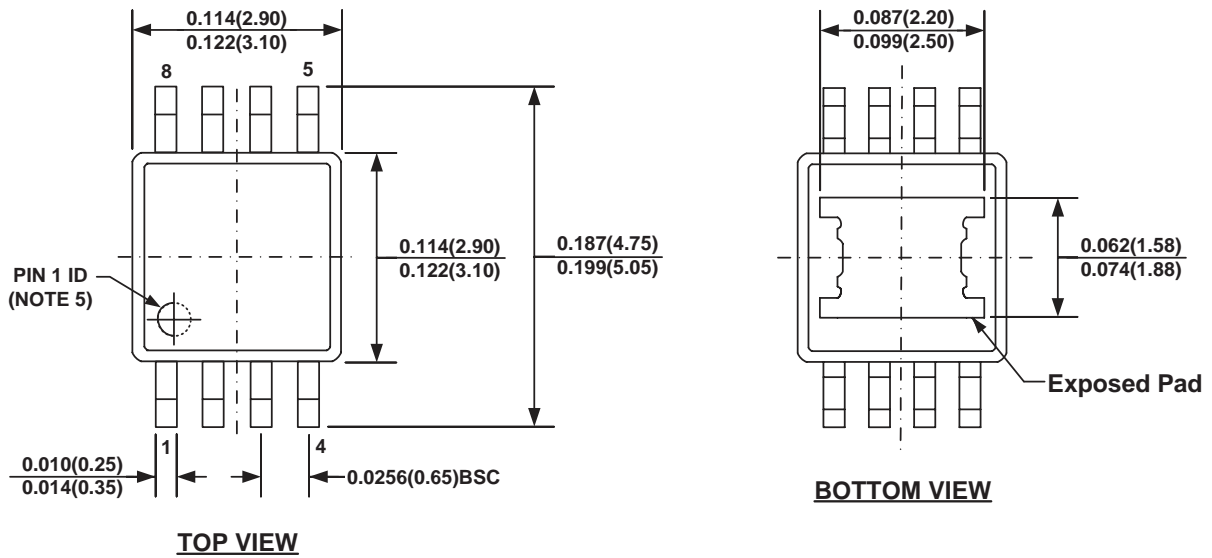
Logic HIGH, the MP6215 is enabled.

APPLICATION INFORMATION

Power-Supply Considerations

A ceramic bypass capacitor between IN and GND, close to the device, is recommended. Placing a high-value electrolytic capacitor on the output pin(s) is recommended when the output load is heavy. This precaution reduces power-supply transients that may cause ringing on the input. Optionally, bypassing the output with a ceramic capacitor improves the immunity of the device to short-circuit transients.

PACKAGE INFORMATION

MSOP8E (EXPOSED PAD)

0.114(2.90)
0.122(3.10)

8   5

0.114(2.90)
0.122(3.10)

0.187(4.75)
0.199(5.05)

PIN 1 ID
(NOTE 5)

1   4

0.010(0.25)
0.014(0.35)

0.0256(0.65)BSC

TOP VIEW

0.087(2.20)
0.099(2.50)

0.062(1.58)
0.074(1.88)

Exposed Pad

BOTTOM VIEW

0.030(0.75)
0.037(0.95)

0.043(1.10)MAX

SEATING PLANE

0.002(0.05)
0.006(0.15)

FRONT VIEW

GAUGE PLANE
0.010(0.25)

0°-6°

0.016(0.40)
0.026(0.65)

0.004(0.10)
0.008(0.20)

SIDE VIEW

0.100(2.54)

0.075(1.90)

0.181(4.60)

0.040(1.00)

0.016(0.40)

0.0256(0.65)BSC

RECOMMENDED LAND PATTERN

NOTE:

1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS
   IN MILLIMETERS.
2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH,
   PROTRUSION OR GATE BURR.
3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR
   PROTRUSION.
4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING)
   SHALL BE 0.004" INCHES MAX.
5) PIN 1 IDENTIFICATION HAS HALF OR FULL CIRCLE OPTION.
6) DRAWING MEETS JEDEC MO-187, VARIATION AA-T.
7) DRAWING IS NOT TO SCALE.